



UVLED375-10-30

1. SPECIFICATIONS

(1) Absolute Maximum Ratings

(Ta=25°C)

Item	Symbol	Absolute Maximum Rating	Unit
Forward Current	I _F	20	mA
Pulse Forward Current	I _{FP}	80	mA
Allowable Reverse Current	I _R	85	mA
Power Dissipation	P _D	80	mW
Operating Temperature	T _{opr}	-30 ~ + 85	°C
Storage Temperature	T _{stg}	-40 ~ +100	°C
Soldering Temperature	T _{slid}	265°C for 10sec.	

I_{FP} Conditions : Pulse Width ≤ 10msec. and Duty ≤ 1/10

(2) Initial Electrical/Optical Characteristics

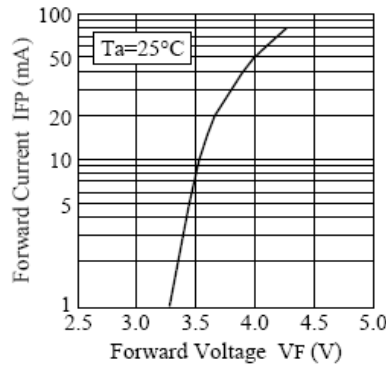
(Ta=25°C)

Item	Symbol	Condition	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	I _F =15[mA]	-	(3.6)	4.0	V
Peak Wavelength	Rank Ub λ _P	I _F =15[mA]	370	(375)	380	nm
Spectrum Half Width	Δλ	I _F =15[mA]	-	(15)	-	nm
Optical Power Output	Rank 7 P _o	I _F =15[mA]	4800	-	6800	μW
	Rank 8 P _o	I _F =15[mA]	6800	-	9600	μW
	Rank 9 P _o	I _F =15[mA]	9600	-	13600	μW

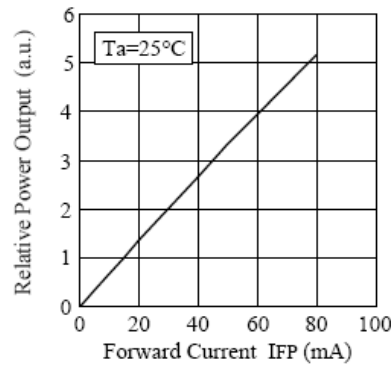




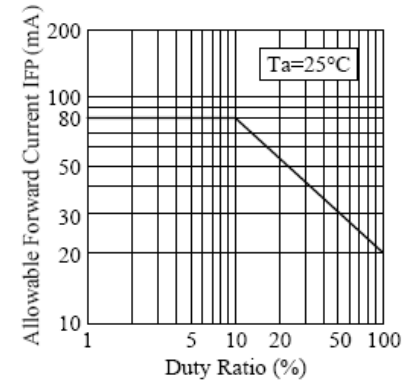
■ Forward Voltage vs. Forward Current



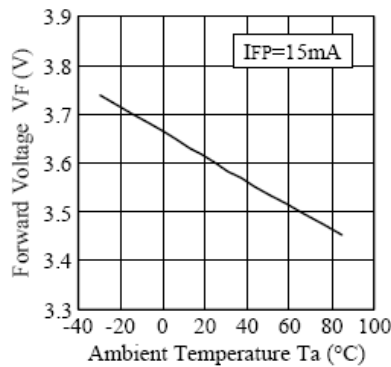
■ Forward Current vs. Relative Power Output



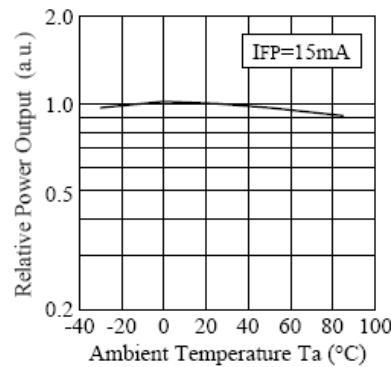
■ Duty Ratio vs. Allowable Forward Current



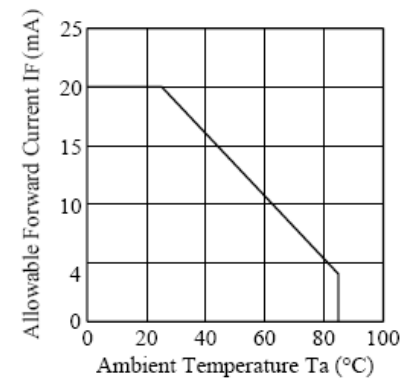
■ Ambient Temperature vs. Forward Voltage



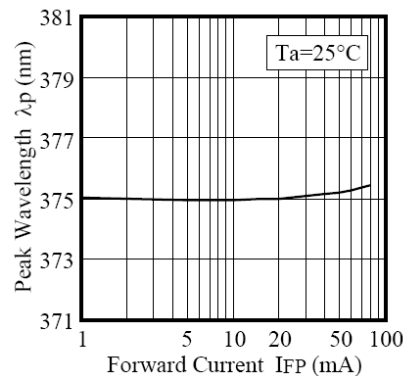
■ Ambient Temperature vs. Relative Power Output



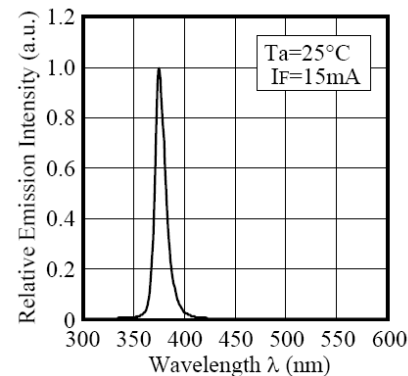
■ Ambient Temperature vs. Allowable Forward Current



■ Forward Current vs. Peak Wavelength

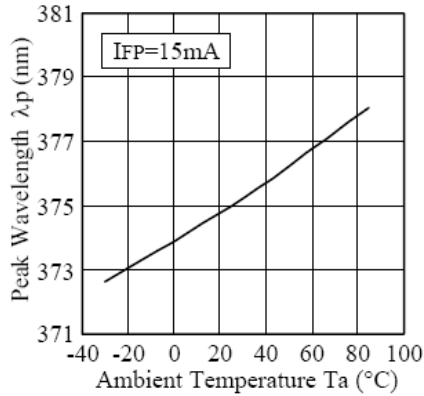


■ Spectrum

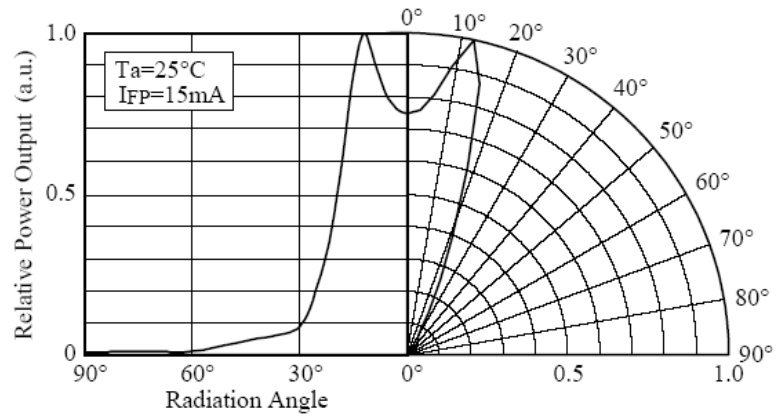




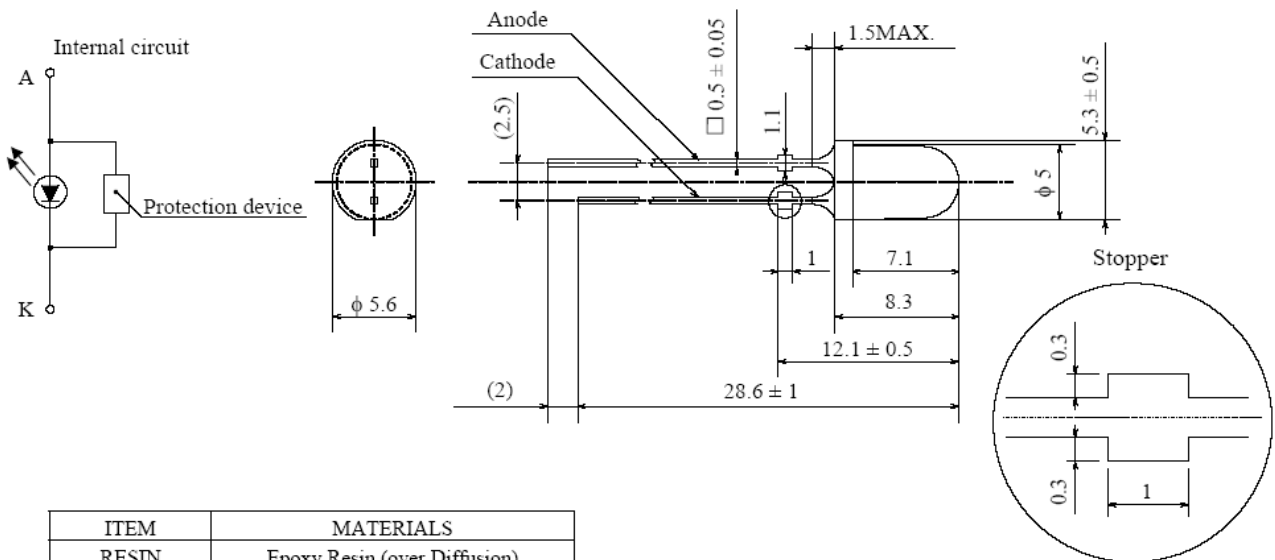
■ Ambient Temperature vs. Peak Wavelength



■ Directivity



Drawing:



ITEM	MATERIALS
RESIN	Epoxy Resin (over Diffusion)
LEAD FRAME	Ag Plating Copper Alloy